



## TSMC Special Board of Directors Meeting Resolution

**HSINCHU, Taiwan, R.O.C., May 10, 2024** – The TSMC (TWSE: 2330, NYSE: TSM) Board of Directors today held a special meeting, which passed the following resolutions:

1. Approved the 2024 first quarter Business Report and Financial Statements. First quarter consolidated revenue totaled NT\$592.64 billion and net income was NT\$225.49 billion, with diluted earnings per share of NT\$8.70.
2. Approved the distribution of a NT\$4.00 per share cash dividend for the first quarter of 2024, and set September 18, 2024 as the record date for common stock shareholders entitled to participate in this cash dividend distribution, and the ex-dividend date for the common shares shall be September 12, 2024. As required by Article 165 of Taiwan's Company Law, the shareholders' register shall be closed for five days prior to the record date (September 14 through September 18, 2024) for registration transfer, and the dividend will be paid on October 9, 2024. In addition, the ex-dividend date for TSMC American Depositary Shares (ADSs) will be September 12, 2024. Beginning May 28, 2024, the New York Stock Exchange will shorten the securities settlement cycle from two business days to one business day, and the record date for TSMC ADSs entitled to participate in this cash dividend distribution will also be September 12, 2024.

### About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,895 products for 528 customers in 2023 by providing broadest range of advanced, specialty and advanced packaging technology services. The Company is headquartered in Hsinchu, Taiwan. For more information please visit <https://www.tsmc.com>.

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